

ABSTRACT AMENDMENTS

Replace the paragraph at page 84, lines 2-7 with the following paragraph:

~~A semiconductor chip assembly includes a semiconductor chip that includes a conductive pad, a conductive trace that includes a routing line and a pillar, a connection joint that electrically connects the routing line and the pad, and an encapsulant. The routing line extends laterally from the pillar towards the chip, the pillar includes tapered sidewalls, and the chip and the pillar are embedded in the encapsulant and extend vertically beyond the routing line in the same direction.~~
A method of making a semiconductor chip assembly includes forming a routing line on a metal base, etching the metal base wherein an unetched portion of the metal base forms a pillar, mechanically attaching a semiconductor chip to the routing line and the pillar wherein the chip includes a conductive pad, the routing line extends laterally from the pillar towards the chip and the chip and the pillar extend vertically beyond the routing line in the same direction, forming an encapsulant wherein the chip and the pillar are embedded in the encapsulant, and forming a connection joint that electrically connects the routing line and the pad.